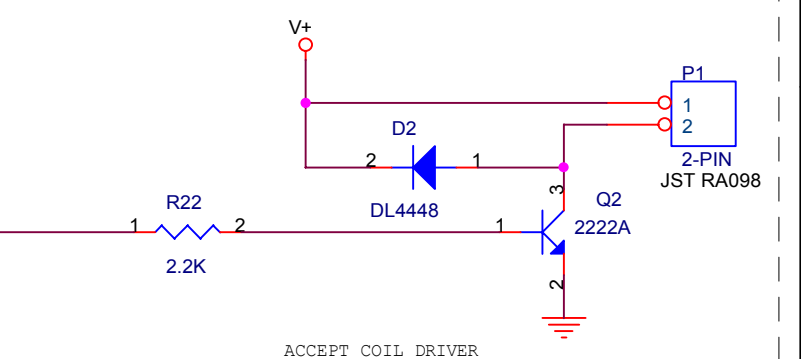
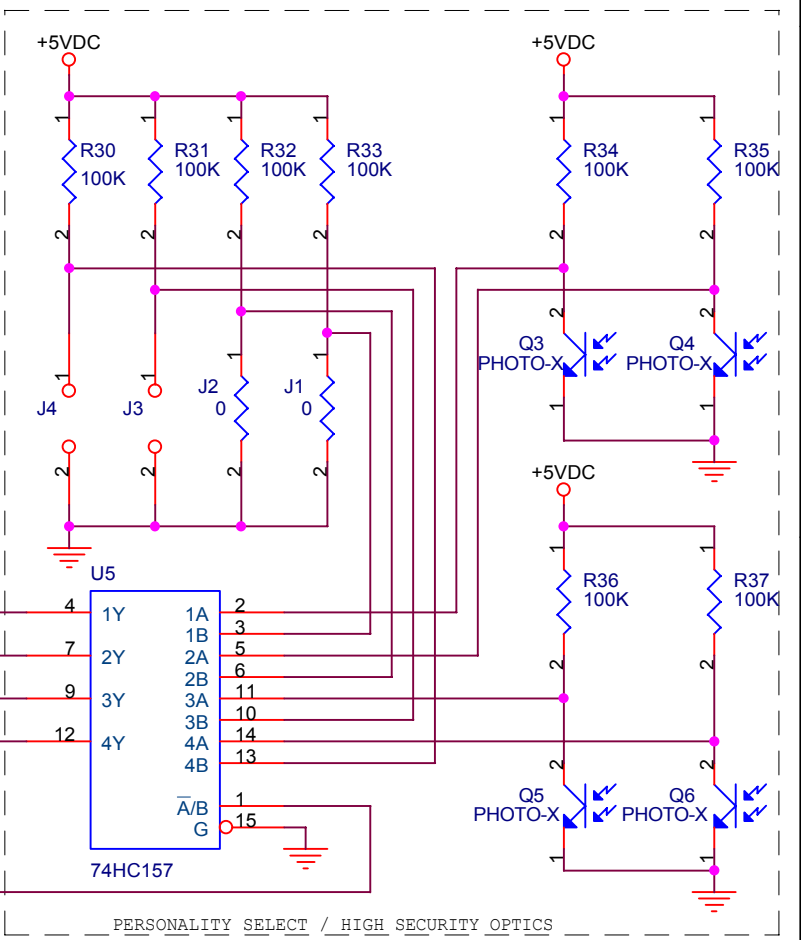



NOTE:
IF Y1 IS M-TRON (ATS-49-12.00) -> C9 & C10 MUST BE 27pF

NO.	ECO #	REVISIONS	DATE BY
0	004920	NEW RELEASE	9/16/97 GH
1	004969	Add D8"DL4448" Remove C11	10/21/97 BPP
2	005116	ADD R44	1/8/98 BPP
3	005150	ADD C11,C16	2/10/98 BPP
4	006173	CHANGE TITLE FROM CC46 TO MC40 PROJECT #99002	3/2/00 BPP
05	006456	C11 VOLTS RATING WAS 50VDC P#01024, ADD SOCKET 0836-000002 TO SHEET 1, 2 AND 3 P#01024, CHANGE U1MICRO FROM 09290168 TO 09290360	8/11/00 SJS 04/23/01 SJS

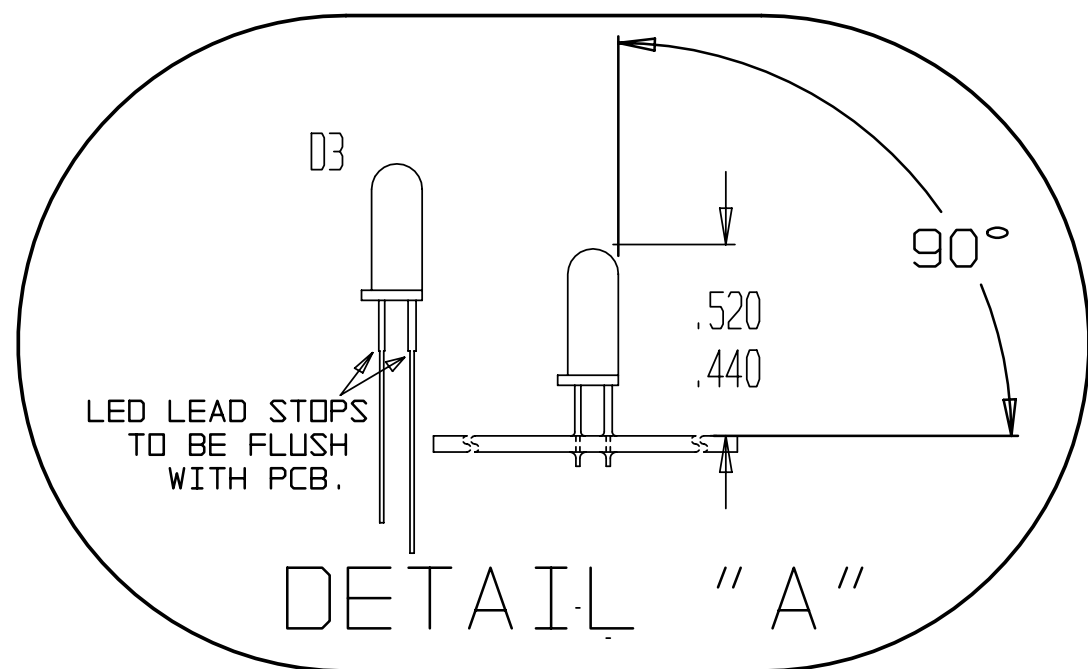
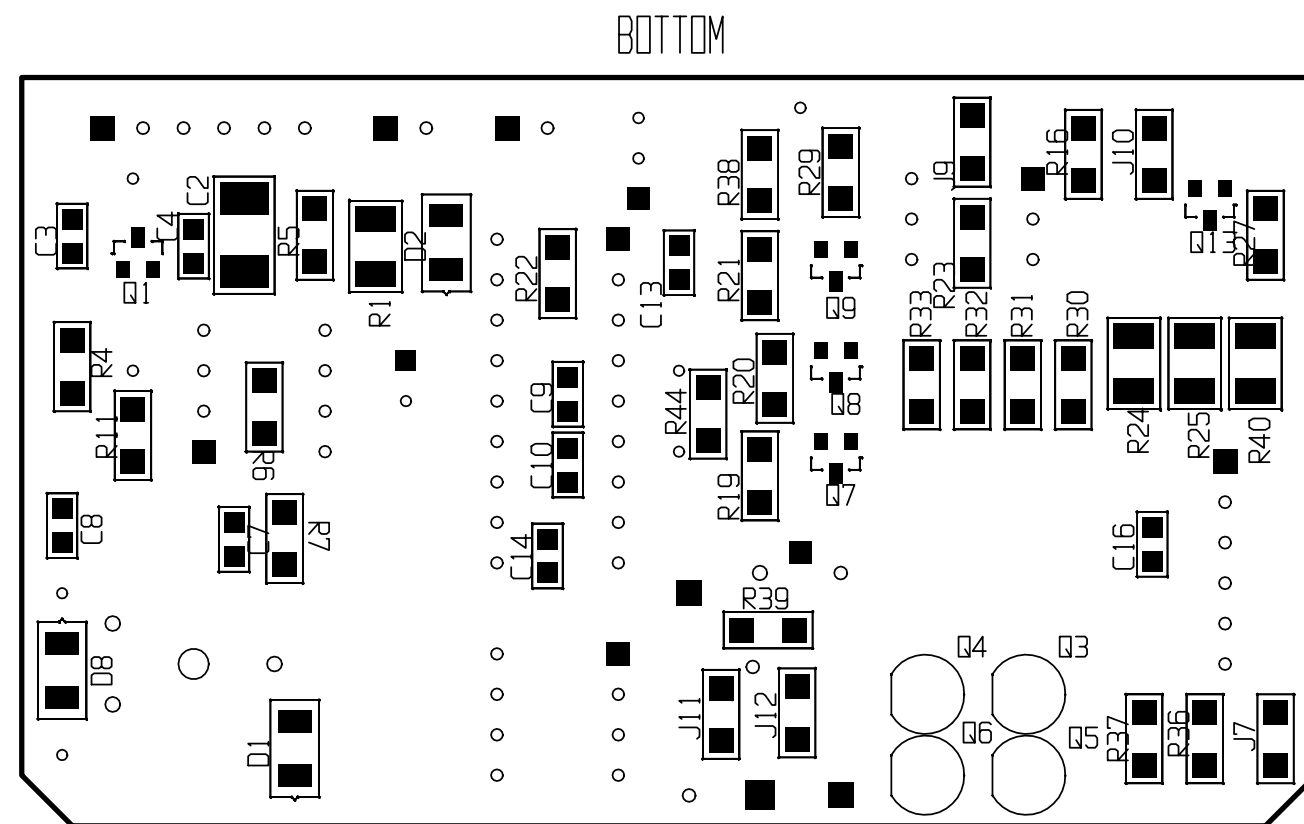
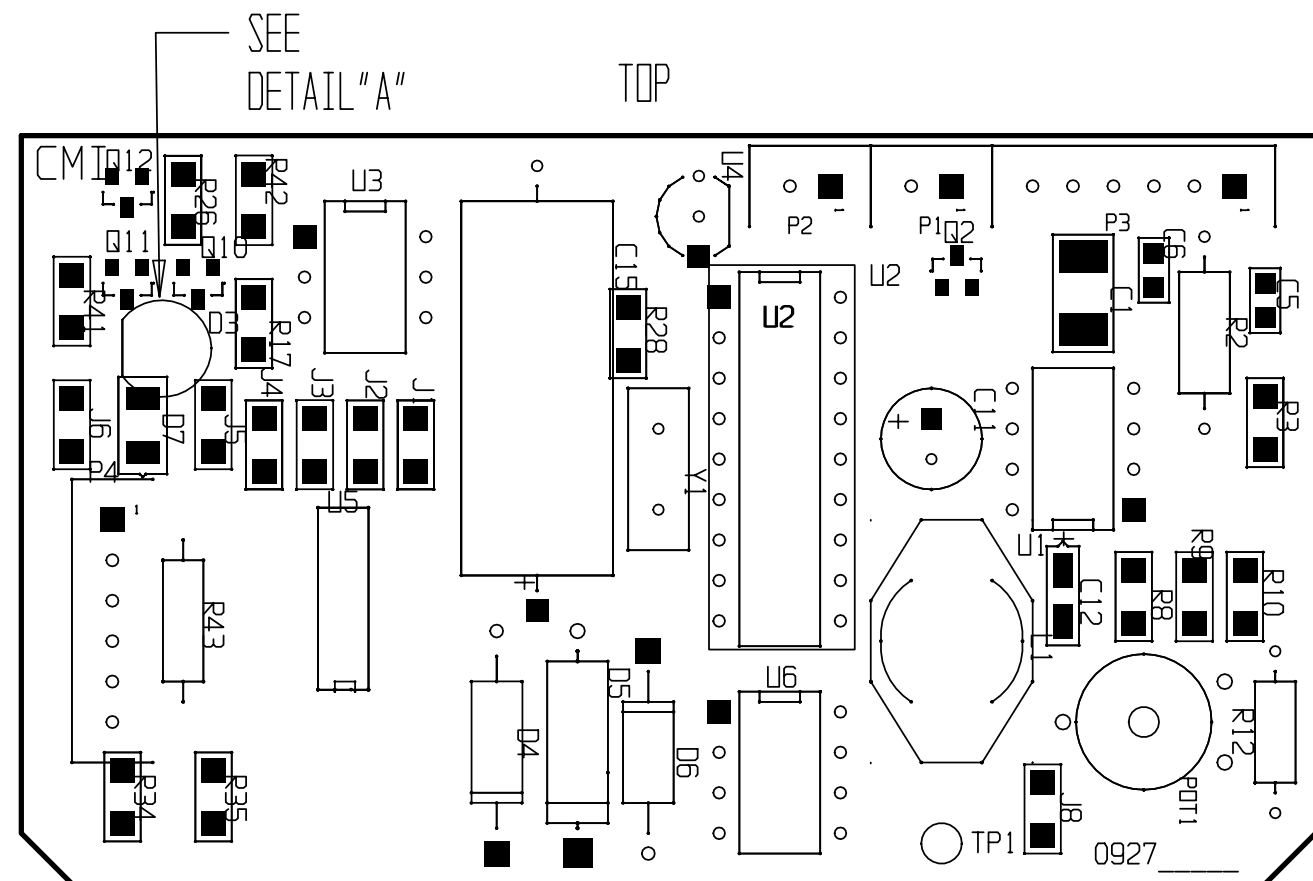




COIN MECHANISMS INC.
400 REGENCY DRIVE
GLENDALE HEIGHTS, IL 60139

TITLE PCB,CTRL,MC40,12VDC, C25MS,T13S,PR3,6PIN	
DRAWN GH	DATE 9/22/97
APP	DATE
DWG # 09270261	REV 5
SIZE B	SHT 1 OF 3


NO.	ECN NO.	REVISIONS	DATE/BY
06	6456	SEE SHEET 1	06/11/01 SJS



NOTES:

1. REFER TO SCHEMATIC DIAGRAM AND PARTS LIST FOR REFERENCE DESIGNATIONS AND COMPONENT VALUES
2. MAXIMUM HEIGHT FOR ANY COMPONENT TO BE .450" EXCEPT FOR LED.
3. MAXIMUM COMPONENT LEAD PROJECTION TO BE .085".
4. SOLDERING SHALL BE IN ACCORDANCE WITH IPC-S-815.
5. ASSEMBLIES TO BE CLEANED OF FLUX AND OTHER CONTAMINANTS AFTER SOLDERING.
6. LEDS TO BE VERTICAL TO PCB DURING SOLDERING PROCESS (SEE DETAIL A).
7. CONNECTORS TO BE FLUSH TO PCB DURING SOLDERING PROCESS.
8. Q3-Q6 MUST BE FLUSH AND PERPENDICULAR TO BOARD.

g:\elec\dwg-rel\0927-9.2

 COIN MECHANISMS INC. 400 REGENCY DR. GLENDALE HGTS, IL	TITLE		
	PCB, CTRL, MC40, 12VDC C25MS, T13S, PR3, 6 PIN		
	DRAWN	KDH	DATE 7/31/97
	CHKD		DATE
This drawing is the property of and contains proprietary information of Coin Mechanisms, Inc. The drawing shall be returned upon request and will not be used in any way detrimental to the interest of Coin Mechanisms, Inc.	APP		DATE
	DWG NO.	09270261	REV 6
SIZE B SCALE X=X		SHT 2 OF 3	